L Number	Hits	Search Text	DB	Time stamp
166	1240	,	USPAT;	2003/09/15 15:27
}		carrier tape)) and (flipchip (flip adj	US-PGPUB;	ł
j (		chip))	EPO; JPO;	j
1			DERWENT	
167	291	((flexible nearl (film board substrate	USPAT;	2003/09/15 15:28
ļ j		carrier tape)) and (flipchip (flip adj	US-PGPUB;	}
j		chip))) and (solder adj (resist mask))	EPO; JPO;	[
] [			DERWENT	İ
168	10525	control\$3 with (flowing flow) with	USPAT;	2003/09/15 15:32
1		(underfill\$3 resin sealing)	US-PGPUB;	[
1			EPO; JPO;	ì
) i	_		DERWENT	
169	0	(((120)2010 110011 (1110) 110010 1100011000	USPAT;	2003/09/15 15:30
		carrier tape)) and (flipchip (flip adj	US-PGPUB;	j l
}		<pre>chip))) and (solder adj (resist mask)))</pre>	EPO; JPO;	1
1		and (control\$3 with (flowing flow) with	DERWENT	[
) i		(underfill\$3 resin sealing);		
[170]	4	((flexible near1 (film board substrate	USPAT;	2003/09/15 15:30
		carrier tape)) and (flipchip (flip adj	US-PGPUB;	[
		chip))) and (control\$3 with (flowing flow)	EPO; JPO;	Ì
1	5.5	with (underfill\$3 resin sealing))	DERWENT	0000 (00 (05 05 05
171	35	(((flexible near) (film board substrate	USPAT;	2003/09/15 15:32
]		carrier tape)) and (flipchip (flip adj	US-PGPUB;	<b>{</b>
		chip))) and (solder adj (resist mask)))	EPO; JPO;	j
}		and ((flowing flow) with (underfill\$3	DERWENT	
		resin sealing))	L	